

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
KOSUKE TAKADA	02/24/2017
RECEIVING PARTY DATA	
Name:	SII SEMICONDUCTOR CORPORATION
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City:	CHIBA-SHI, CHIBA
State/Country:	JAPAN
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15449320
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NAME OF SUBMITTER:	TADASHI HORIE
SIGNATURE:	/Tadashi Horie/
DATE SIGNED:	03/03/2017
Total Attachments: 2	
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ASSIGNMENT

WHEREAS, Kosuke TAKADA, hereinafter called the "Assignor", has made the invention described in the United States patent application entitled OUTPUT CIRCUIT, executed by Assignor on the same date as, or on a date prior to, this Assignment;

WHEREAS, SII Semiconductor Corporation, a corporation organized and existing under the laws of Japan, having a place of business at 8, Nakase 1-chome, Mihama-ku, Chiba-shi, Chiba, Japan 261-8507, hereinafter called the "Assignee", desires to acquire the entire right, title and interest in and to the invention and the patent application identified above, and all patents which may be obtained for said invention, as set forth below;

NOW, THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other valuable and legally sufficient consideration, the receipt of which by the Assignor from the Assignee is hereby acknowledged, the Assignor has sold, assigned and transferred, and by these presents do sell, assign and transfer to the Assignee, the entire right, title and interest for the United States in and to the invention and the patent application identified above, and any patents that may issue for said invention in the United States; together with the entire right, title and interest in and to said invention and all patent applications and patents therefor in all countries foreign to the United States, including the full right to claim for any such application all benefits and priority rights under any applicable convention; together with the entire right, title and interest in and to all continuations, divisions, renewals and extensions of any of the patent applications and patents defined above; to have and to hold for the sole and exclusive use and benefit of the Assignee, its successors and assigns, to the full end of the term or terms for all such patents.

The Assignor hereby covenants and agrees, for both the Assignor and the Assignor's legal representatives, that the Assignor will assist the Assignee in the prosecution of the patent application identified above; in the making and prosecution of any other patent applications that the Assignee may elect to make covering the invention identified above; in vesting in the Assignee like exclusive title in and to all such other patent applications and patents; and in the prosecution of any interference which may arise involving said invention, or any such patent application or patent; and that the Assignor will execute and deliver to the

